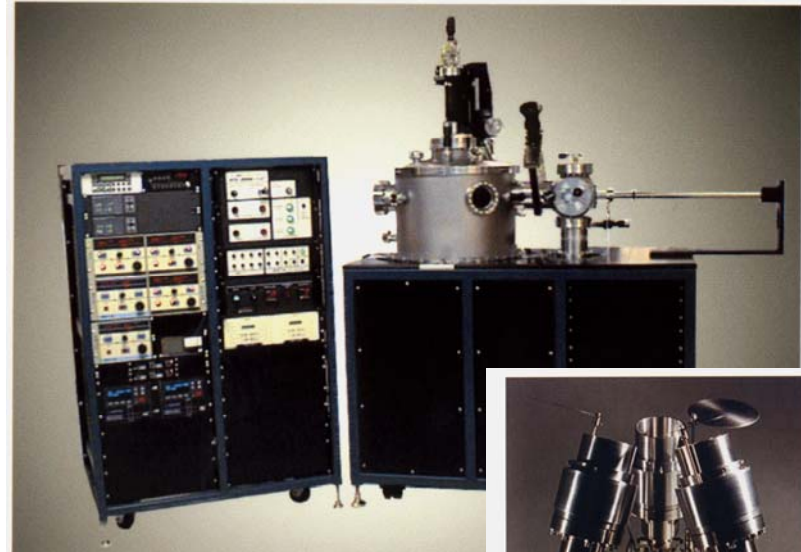


Sputtering capabilities

- 3 guns, co-sputtering cluster
- 2" x 1/4" disk targets
- RF and DC magnetron, magnetic and non-magnetic metals, custom alloys, oxides and nitrides
- typical targets: Cu, Al, Ti, Au, Pt, Ir, Ni, W, V, Ni-V, Pt-Ru
- Substrates: 3" Si wafers (standard), smaller samples also possible
- base pressure 3×10^{-7} torr
- substrate bias, reactive sputtering, and substrate heating capability
- in-situ substrate curvature (film stress) measurement is possible



Images courtesy of AJA International

